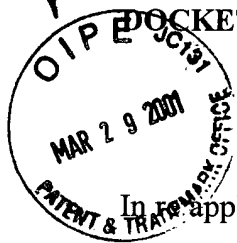


Phil Amundson
10/16/01



POCKET NO. 93-C-077C1 (STMI01-93077)

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In application of : Loi N. Nguyen, et al.
U.S. Serial No. : 09/712,827
Filed : November 14, 2000
For : METHOD AND INTERLEVEL DIELECTRIC STRUCTURE
FOR IMPROVED METAL STEP COVERAGE
Group No. : 2835
Examiner : (Not Yet Known)

BOX MISSING PARTS
Assistant Commissioner for Patents
Washington, D. C. 20231

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Box Missing Parts, Commissioner of Patents and Trademarks, Washington, D.C. 20231, on 3-26-01 (Date)

Daniel E. Venglarik
(Printed or typed name of person signing the certificate)

Daniel E. Venglarik
(Signature of the person signing the certificate)

Sir:

PRELIMINARY AMENDMENT

No fees are believed to be necessary; however, in the event that any fees are required for the prosecution of this application, please charge any necessary fees to Deposit Account No. 50-0208. No extension of time is believed to be necessary. If, however, an extension of time is needed, the extension is requested and please charge the fee for this extension to Deposit Account No. 50-0208.

Prior to examination and computation of the required filing fee, please amend the above-identified application as follows:

A